



Material Content Data Sheet



Sales Product Name				IAUC60N04S6N044		Issued		12. August 2019	
MA#				MA001701712					
Package				PG-TDSON-8-33		Weight*		111.25 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.285	0.26	0.26	2558	2558	
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		143		
	non noble metal	iron	7439-89-6	0.053	0.05		476		
	non noble metal	copper	7440-50-8	52.842	47.49	47.55	475002	475621	
	noble metal	gold	7440-57-5	0.044	0.04	0.04	398	398	
wire	noble metal	gold	7440-57-5	0.044	0.04	0.04	398	398	
encapsulation	organic material	carbon black	1333-86-4	0.077	0.07		694		
	plastics	epoxy resin	-	6.099	5.48		54828		
	inorganic material	silicondioxide	60676-86-0	32.427	29.15	34.70	291488	347010	
leadfinish	non noble metal	tin	7440-31-5	1.574	1.41	1.41	14147	14147	
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1881	1881	
solder	non noble metal	tin	7440-31-5	0.009	0.01		83		
	noble metal	silver	7440-22-4	0.012	0.01		103		
	non noble metal	lead	7439-92-1	0.440	0.40	0.42	3951	4137	
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		45		
	non noble metal	iron	7439-89-6	0.017	0.02		151		
	non noble metal	copper	7440-50-8	16.828	15.13	15.15	151265	151461	
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	iron	7439-89-6	0.000	0.00		3		
	non noble metal	copper	7440-50-8	0.310	0.28	0.28	2783	2787	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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